Product data sheet

1. General description

Planar passivated high commutation three quadrant triac in a SOT78D (IITO-220) internally insulated plastic package with selfprotective clamping capabilities against low and high energy transients. This triac will commutate the full RMS current at the maximum rated junction temperature ($T_{\text{j(max)}}$) = 150 °C) without the aid of a snubber. It is used in circuits where high static and dynamic dV/dt and high dI/dt can occur and in applications where "high junction operating temperature capability" is required.

2. Features and benefits

- · Clamping structure ensuring safe high over-voltage withstand capability
- High junction operating temperature capability (T_{j(max)} = 150 °C)
- High minimum I_{GT} for guaranteed immunity to gate noise
- Full cycle AC conduction
- Over-voltage withstand capability to IEC 61000-4-5
- · Internally insulated package
- · Isolated mounting base with 2500 V (RMS) isolation
- · Protective self turn-on capability for high energy transients
- Safe clamping capability for low energy over-voltage transients
- · Less sensitive gate for high noise immunity
- Triggering in three quadrants only
- Planar passivated for voltage ruggedness and reliability

3. Applications

- Applications subject to high temperature (T_{i(max)} = 150 °C)
- Electronic themostats (heating and cooling)
- · High power motor controls e.g washing machine and vacuum cleaners
- Rectifier-fed DC inductive loads e.g DC motors and solenoids
- Refrigeration and air conditioning compressors

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values	Unit
Absolute	maximum rating			
V_{DRM}	repetitive peak off-state voltage		800	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \le 112 ^{\circ}\text{C}$; Fig. 1; Fig. 2; Fig. 3	16	Α
I _{TSM}	non-repetitive peak on- state current	full sine wave; $t_p = 20 \text{ ms}$; $T_{J(init)} = 25 \text{ °C}$; Fig. 4; Fig. 5	160	А
		full sine wave; $t_p = 16.7 \text{ ms}$; $T_{j(init)} = 25 \text{ °C}$	176	Α
T _j	junction temperature		150	°C

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static cha	racteristics					
I _{GT}	gate trigger current	$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2 + G + T_j = 25 \text{ °C; } Fig. 7$	-	-	50	mA
		$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2 + G-$ $T_j = 25 \text{ °C; } Fig. 7$	-	-	50	mA
		$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; T2- G-} $ $T_j = 25 \text{ °C; Fig. 7}$	-	-	50	mA
I _H	holding current	V _D = 12 V; T _j = 25 °C; <u>Fig. 9</u>	-	-	60	mA
V _T	on-state voltage	I _T = 20 A; T _j = 25 °C; <u>Fig. 10</u>	-	-	1.5	V
Dynamic	characteristics					
dV _D /dt	rate of rise of off-state voltage	V_{DM} = 536 V; T_j = 125 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; gate open circuit	1000	-	-	V/µs
		V_{DM} = 536 V; T_j = 150 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; gate open circuit	600	-	-	V/µs
dl _{com} /dt	rate of change of commutating current	V_D = 400 V; T_J = 150 °C; $I_{T(RMS)}$ = 16 A; dV_{com}/dt = 20 V/ μ s; gate open circuit; snubberless condition	15	-	-	A/ms

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	T1	main terminal 1		T2—T1
2	T2	main terminal 2		sym051
3	G	gate		Symoor
mb	n.c	mounting base; isolated	IITO-220 (SOT78D)	

6. Ordering information

Table 3. Ordering information

Type number	Package				
	Name	Description	Version		
BTA316Y-800BT	IITO-220	Plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3 leads TO-220	IITO-220E		

7. Marking

Table 4. Marking codes

Type number	Marking codes
BTA316Y-800BT	BTA316Y-800BT

BTA316Y-800BT

8. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
V_{DRM}	repetitive peak off-state voltage		800	V
I _{T(RMS)}	RMS on-state current	full sine wave; $T_{mb} \le 112^{\circ}C$; <u>Fig. 1</u> ; <u>Fig. 2</u> ; <u>Fig. 3</u>	16	А
I _{TSM}	non-repetitive peak on- state current	full sine wave; t_p = 20 ms; $T_{j(init)}$ = 25 °C; Fig. 4; Fig. 5	160	А
		full sine wave; t_p = 16.7 ms; $T_{j(init)}$ = 25 °C	176	А
l ² t	I ² t for fusing	t _p = 10ms; sine wave	128	A ² s
dl _⊤ /dt	rate of rise of on-state current	I _G = 150mA	100	A/µs
I _{GM}	peak gate current		2	А
P_{GM}	peak gate power		5	W
$P_{G(AV)}$	average gate power	over any 20 ms period	0.5	W
T _{stg}	storage temperature		-40 to 150	°C
T _j	junction temperature		150	°C

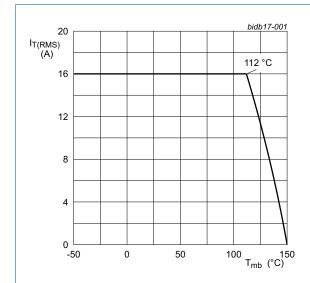


Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values

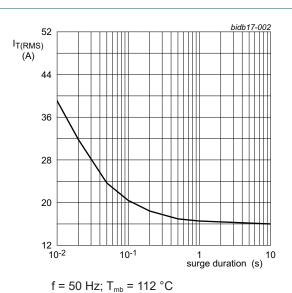


Fig. 2. RMS on-state current as a function of surge duration; maximum values

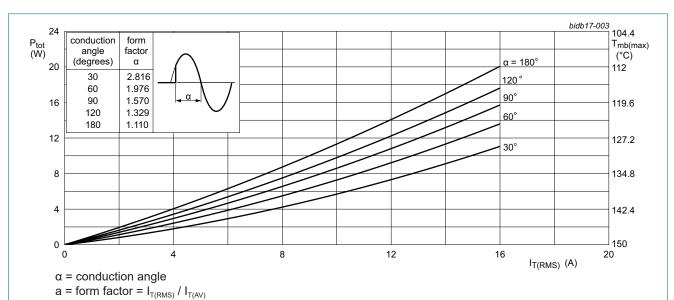


Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values

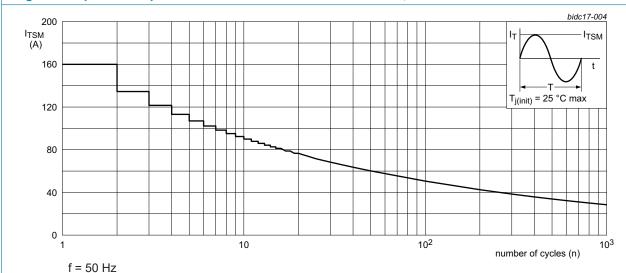
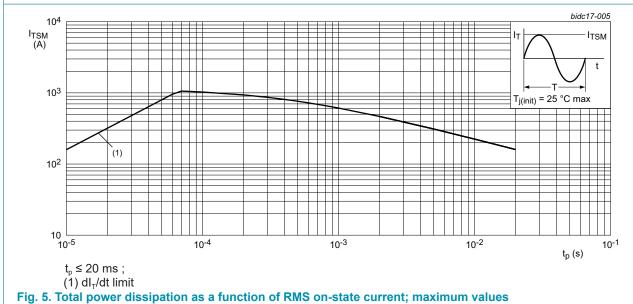


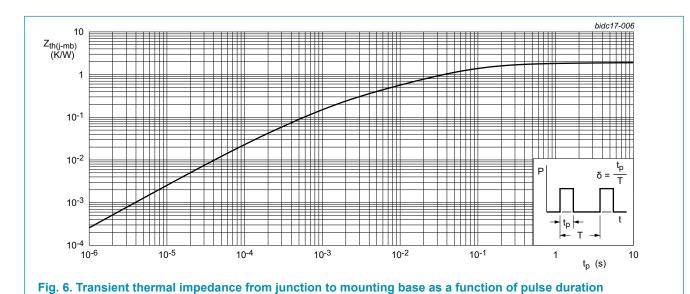
Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



9. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R _{th(j-mb)}	thermal resistance from junction to mounting base	Fig. 6	-	-	1.9	K/W
R _{th(j-a)}	thermal resistance from junction to ambient free air	in free air	-	60	-	K/W



10. Isolation characteristics

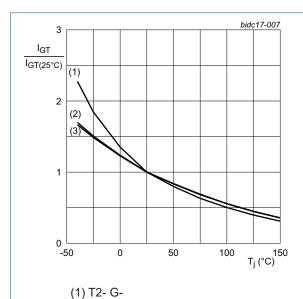
Table 6. Isolation characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{isol(RMS)}	RMS isolation voltage	50 Hz ≤ f ≤ 60 Hz; RH ≤ 65 %; from all pins to external heatsink; sinusoidal waveform; clean and dust free	-	-	2500	V
C _{isol}	isolation capacitance	from cathode to external heatsink	-	10	-	PF

11. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static cha	racteristics					
I _{GT}	gate trigger current	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T2+ G+;$ $T_j = 25 \text{ °C}; Fig. 7$	-	-	50	mA
		$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T2+ \text{ G-};$ $T_j = 25 \text{ °C}; Fig. 7$	-	-	50	mA
		$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2- \text{ G-;}$ $T_j = 25 \text{ °C; } \underline{\text{Fig. 7}}$	-	-	50	mA
I _L	latching current	$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2+ \text{ G+;} $ $T_j = 25 \text{ °C; } Fig. 8$	-	-	70	mA
		$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T2+ \text{ G-};$ $T_j = 25 ^{\circ}\text{C}; \underline{\text{Fig. 8}}$	-	-	80	mA
		$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; \text{ T2- G-};$ $T_j = 25 ^{\circ}\text{C}; \underline{\text{Fig. 8}}$	-	-	70	mA
I _H	holding current	V _D = 12 V; T _j = 25 °C; <u>Fig. 9</u>	-	-	60	mA
V _T	on-state voltage	I _T = 20 A; T _j = 25 °C; <u>Fig. 10</u>	-	-	1.5	V
V _{GT}	gate trigger voltage	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_j = 25 \text{ °C};$ Fig. 11	-	0.8	1	V
		$V_D = 400 \text{ V}; I_T = 0.1 \text{ A}; T_j = 150 \text{ °C};$ Fig. 11	0.2	0.45	-	V
I _D	off-state current	V _D = 800 V; T _j = 25 °C	-	-	5	μA
		V _D = 800 V; T _j = 150 °C	-	-	2	mA
Dynamic o	haracteristics		'	'		_
dV _D /dt	rate of rise of off-state voltage	V_{DM} = 536 V; T_j = 125 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; gate open circuit	1000	-	-	V/µs
		V_{DM} = 536 V; T_j = 150 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; gate open circuit	600	-	-	V/µs
dI _{com} /dt	rate of change of commutating current	V_D = 400 V; T_j = 150 °C; $I_{T(RMS)}$ = 16 A; dV_{com}/dt = 20 V/ μ s; gate open circuit; snubberless condition	15	-	-	A/ms
		V_D = 400 V; T_j = 150 °C; $I_{T(RMS)}$ = 16 A; dV_{com}/dt = 10 V/ μ s; gate open circuit; snubberless condition	18	-	-	A/ms
		V_D = 400 V; T_j = 150 °C; $I_{T(RMS)}$ = 16 A; dV_{com}/dt = 1 V/ μ s; gate open circuit; snubberless condition	22	-	-	A/ms



(2) T2+ G-(3) T2+ G+

Fig. 7. Normalized gate trigger current as a function of junction temperature

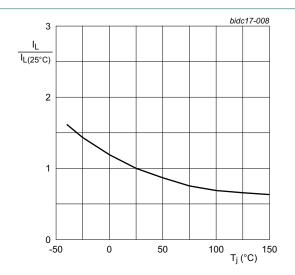


Fig. 8. Normalized latching current as a function of junction temperature

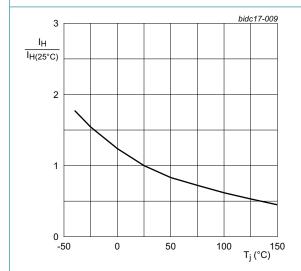
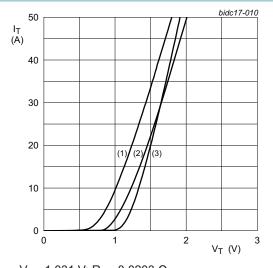


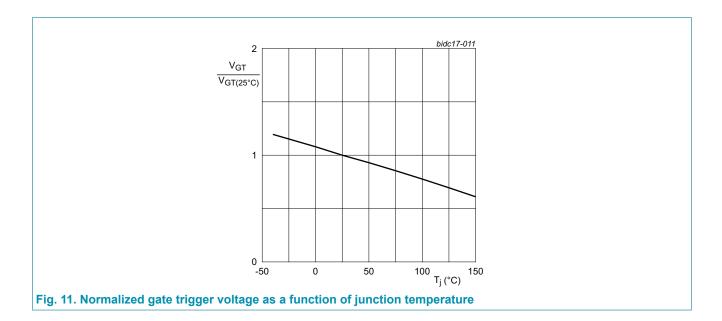
Fig. 9. Normalized holding current as a function of junction temperature



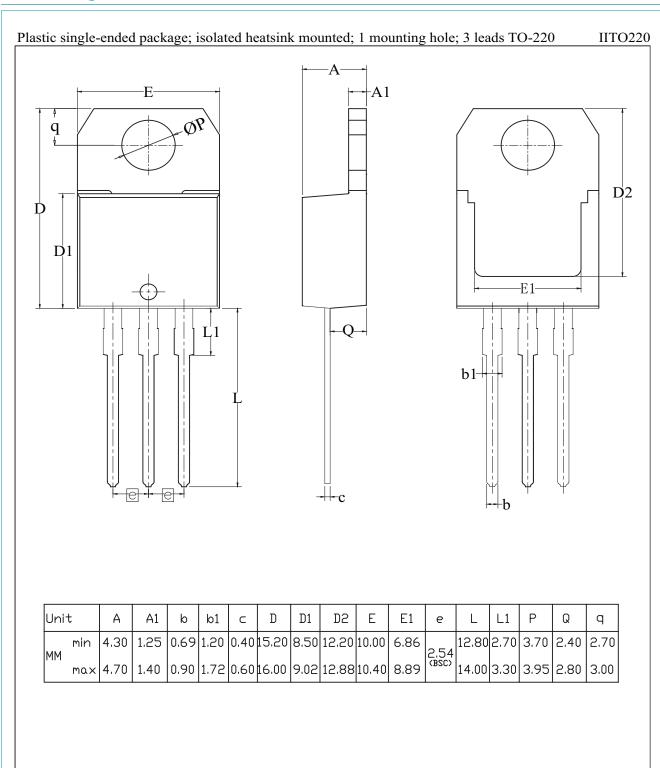
 V_o = 1.031 V; R_s = 0.0203 Ω (1) T_j = 150 °C; typical values (2) T_j = 150 °C; maximum values

(3) T_i = 25 °C; maximum values

Fig. 10. On-state current as a function of on-state voltage



12. Package outline



13. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Product [short] data sheet	Production	This document contains the product specification.

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